



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-28
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement	
Supplier Acceptance *	Legal Declaration *
true	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDO7*1852AR6	A	BO2A	2015-10-28
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.85 - 3.9 - 1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC; MD valid for TS1852IDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDO7*1852AR6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die or Dies	Other inorganic materials	1.447	mg	supplier	die	Silicon (Si)	7440-21-3		1.435	mg	991707	17938	
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3455	63	
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	2764	50	
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.003	mg	2073	38	
Leadframe	Copper & its alloys	34.351	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.434	mg	973305	417925	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.786	mg	22881	9825	
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.047	mg	1368	588	
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.041	mg	1194	513	
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.040	mg	1164	500	
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	29	13	
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	29	13	
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	29	13	
Die attach	Other inorganic materials	0.546	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.497	mg	910256	6213	
Die attach				supplier	glue or tape	acrylate	Proprietary		0.027	mg	49451	338	
Die attach				supplier	glue or tape	Methacrylate	Proprietary		0.022	mg	40293	275	
Bonding wire	Other inorganic materials	0.036		supplier	wire	Copper (Cu)	7440-50-8		0.036	mg	1000000	450	
encapsulation	Other inorganic materials	43.620	mg	supplier	mold compound	Epoxy Resin	Proprietary		3.192	mg	73177	39900	
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		3.192	mg	73177	39900	
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		36.853	mg	844865	460663	
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.213	mg	4883	2663	
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.170	mg	3897	2125	